

MBRS3201P

200 V, 3 A Schottky Fast Soft-Recovery Power Rectifier

SMC Power Surface Mount Package

Features

- Lower Forward Voltage than any Ultrafast Rectifier:
 $V_F < 0.59 \text{ V}$ at 150°C
- Fast Switching Speed: Reverse Recovery Time (t_{RR}) $< 35 \text{ ns}$
- Soft Recovery Characteristics: Softness Factor (t_b/t_a) ≥ 1
- Highly Stable Over Temperature
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Benefits

- Significantly Reduced EMI
- Eliminates the Need of Snubber Circuits
- Low Switching and Heat Losses
- Improved Thermal Management

Applications

- Engine and Convenience Control Systems
- Motor Controls
- Battery Chargers and Switching Power Supplies

Mechanical Characteristics

- Small Compact Surface Mount Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Weight: 217 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- ESD Ratings:
 - ♦ Machine Model = A
 - ♦ Human Body Model = 1C
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- Cathode Polarity Band



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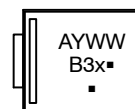
SCHOTTKY RECTIFIER 3 AMPS, 200 VOLTS



SMC 2-LEAD
CASE 403AC



MARKING DIAGRAM



B321 = Specific Device Code
A = Assembly Location*
Y = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

* The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

ORDERING INFORMATION

| Device | Package | Shipping† |
|--------------|-------------------------|-----------------------|
| MBRS3201PT3G | SMC 2-Lead (Pb-Free) | 2500 / Tape & Reel |

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MBRS3201P

MAXIMUM RATINGS

| Characteristic | Symbol | Value | Unit |
|--|---------------------------------|-------------|------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 200 | V |
| Average Rectified Forward Current (Rated V_R , $T_C = 70^\circ\text{C}$) | $I_{F(AV)}$ | 3 | A |
| Nonrepetitive Peak Surge Current | I_{FSM} | 100 | A |
| Operating Junction Temperature | T_J | -55 to +150 | $^\circ\text{C}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|---|-----------------|-------|--------------------|
| Thermal Resistance, Junction-to-Lead | $R_{\theta JL}$ | 12 | $^\circ\text{C/W}$ |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 60 | $^\circ\text{C/W}$ |

ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|---|----------|--------------|----------|
| Maximum Instantaneous Forward Voltage ($I_F = 3\text{ A}$, $T_J = 25^\circ\text{C}$) ($I_F = 3\text{ A}$, $T_J = 150^\circ\text{C}$) | V_F | 0.84 0.59 | V |
| Maximum Instantaneous Reverse Current (Rated V_R) (Rated DC Voltage, $T_J = 25^\circ\text{C}$) (Rated DC Voltage, $T_J = 150^\circ\text{C}$) | I_R | 1.0 5.0 | mA mA |
| Maximum Reverse Recovery Time ($I_F = 1\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$) | t_{rr} | 35 | ns |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

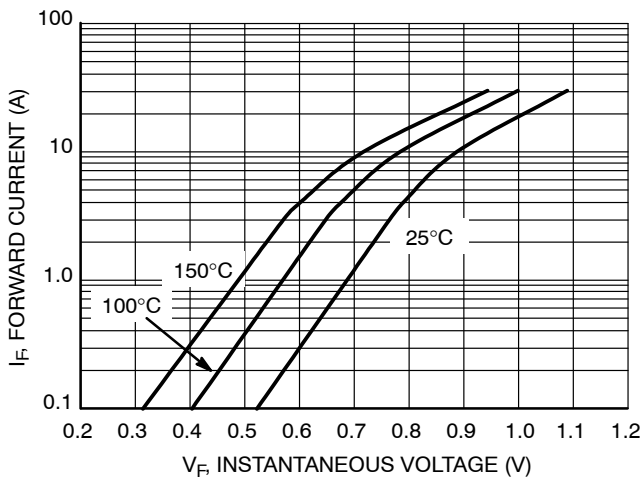


Figure 1. Typical Forward Voltage

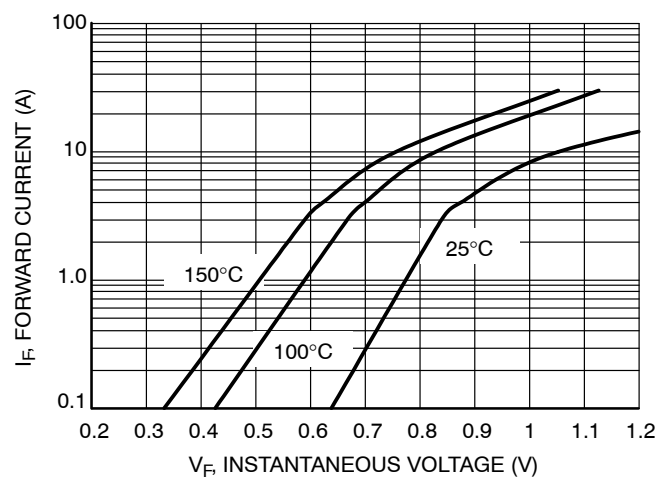


Figure 2. Maximum Forward Voltage

MBRS3201P

TYPICAL CHARACTERISTICS

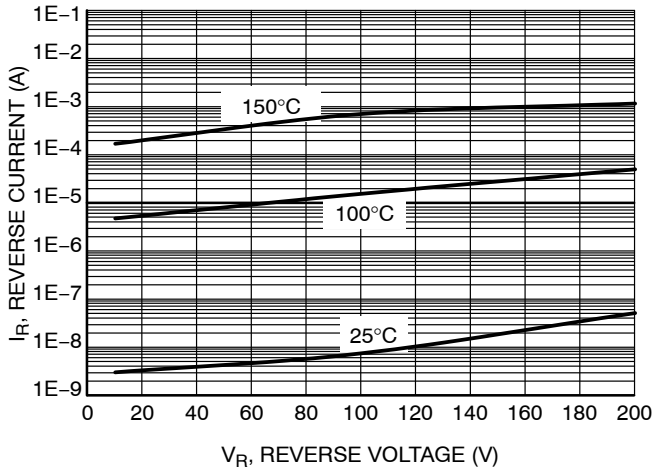


Figure 3. Typical Reverse Current

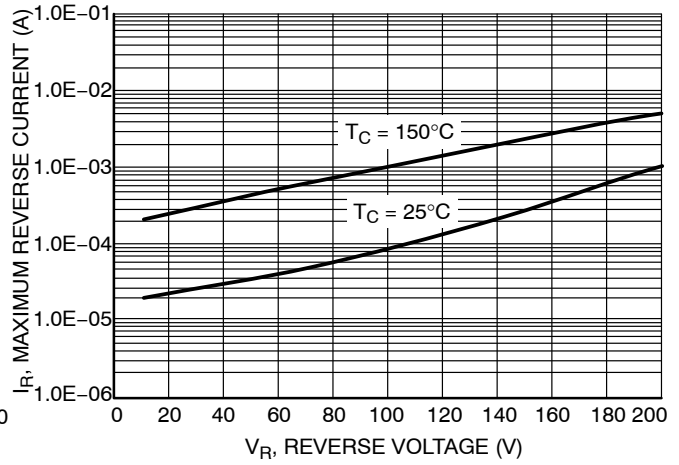


Figure 4. Maximum Reverse Current

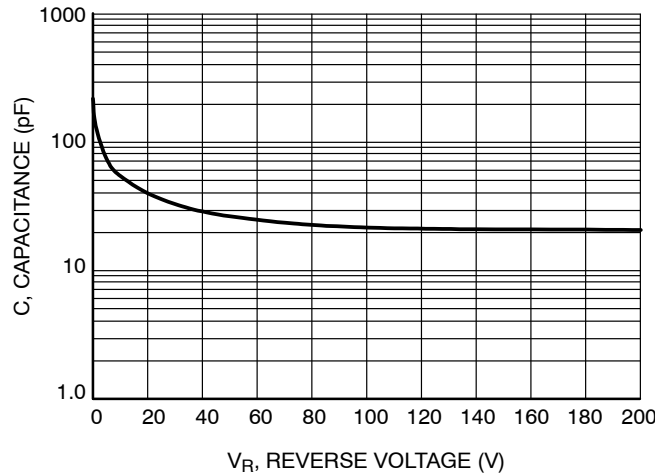


Figure 5. Typical Capacitance

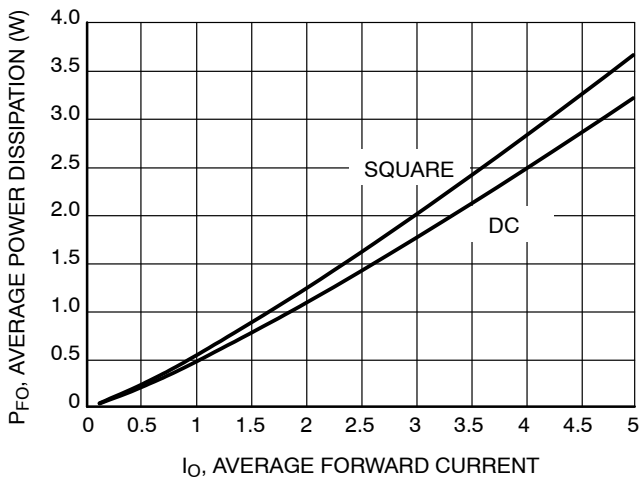


Figure 6. Power Dissipation

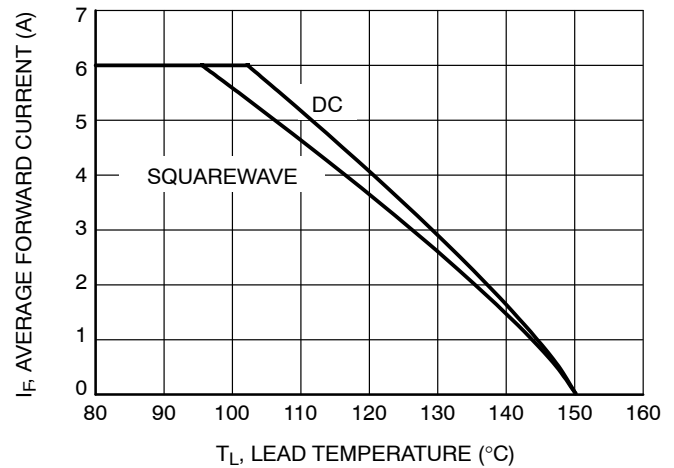


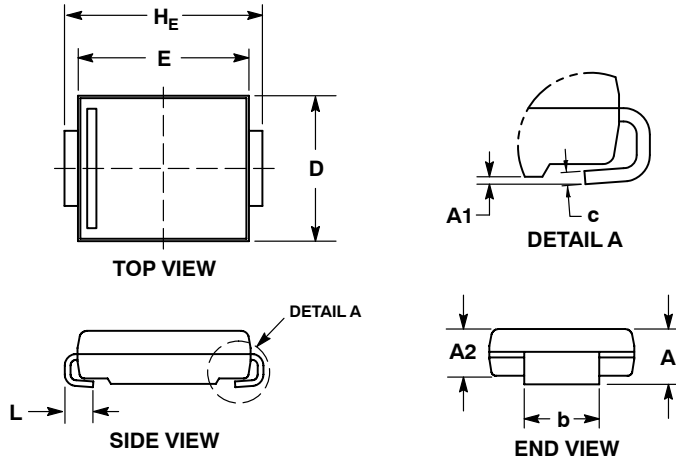
Figure 7. Derating Curve



SCALE 1:1

SMC 2-LEAD
CASE 403AC
ISSUE B

DATE 27 JUL 2017

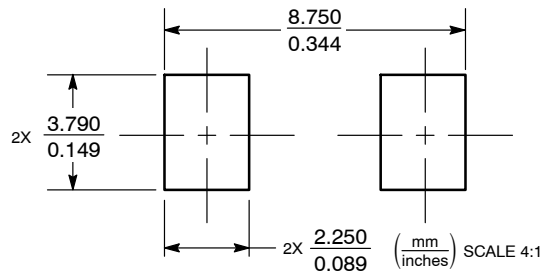


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.254mm PER SIDE.
4. DIMENSIONS D AND E TO BE DETERMINED AT DATUM H.
5. DIMENSION b SHALL BE MEASURED WITHIN THE AREA DETERMINED BY DIMENSION L.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|--------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.95 | 2.61 | 0.077 | 0.103 |
| A1 | 0.05 | 0.20 | 0.002 | 0.008 |
| A2 | 1.90 | 2.41 | 0.075 | 0.095 |
| b | 2.90 | 3.20 | 0.114 | 0.126 |
| c | 0.15 | 0.41 | 0.006 | 0.016 |
| D | 5.55 | 6.25 | 0.219 | 0.246 |
| E | 6.60 | 7.15 | 0.260 | 0.281 |
| HE | 7.75 | 8.15 | 0.305 | 0.321 |
| L | 0.75 | 1.60 | 0.030 | 0.063 |

RECOMMENDED
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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|------------------|-------------|---|
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